

# Qualcomm Dragonwing™ Q-8750 Processor



Bring powerful on-device AI, ultra-clear video, and multi-camera awareness to edge devices and immersive smart displays.

The Dragonwing Q-8750 processor is designed to deliver high-performance video processing and on-device AI for next-generation edge applications across enterprise drones, retail devices, AI TVs, media stations, action cameras, and collaboration systems. Its ability to perform real-time analytics and multi-camera awareness enables devices to interpret and respond to visual data locally, reducing reliance on cloud infrastructure.

With ultra-high-resolution video output, fast connectivity, and integrated AI accelerators, the Dragonwing Q-8750 is designed to support advanced features like motion detection, facial recognition, adaptive content delivery, and autonomous navigation. Its compact design and wide environmental tolerance make it ideal for space-constrained and mission-critical deployments—empowering smarter, more responsive devices that enhance situational awareness, immersive media experiences, and seamless enterprise collaboration.

## Highlights

### Powerful AI, CPU, and GPU

Up to 77 dense TOPS of AI powered by the Qualcomm® Hexagon™ Tensor Processor enables real-time, on-device AI inference and low-latency vision processing. Up to 4.32 GHz clock speed using our custom 7- or 8-core Qualcomm Oryon™ CPU and 1.1 GHz with our Qualcomm® Adreno™ GPU enable top-tier compute and graphics.\*



### Cinematic Visual Experience

Supports 4K/8K video at high frame rates, with ray tracing, advanced graphics, dual-display output, and low-latency rendering.



### Multi-Camera Intelligence

Connects up to 12 physical cameras, 18 logical camera streams, and triple 48 MP ISPs for 360° visibility, depth mapping, and multi-angle recording.



### Fast, Efficient Storage and Interfaces

Integrates UFS 4.0, PCIe Gen 3, and USB-C with DisplayPort to enable ultra-fast data handling and display output.



### Designed for Harsh Environments

With -30 to +105 °C temperature support, it is built for ruggedized applications in automotive and outdoor edge AI systems.



\* Performance may vary by SKU configuration.

## Block Diagram

7- or 8-Core Qualcomm Oryon CPU	Adreno 8-Series GPU
Up to 77 Dense TOPS AI Engine	3840 x 2560 Display
LPDDR5X Memory	Audio DSP (LPASS)
Security	4K240/8K60 Decode 4K120/8K30 Encode
Triple ISP	215x GPIO





## Target Applications

- **Smart Displays:** AI Media Stations, Commercial Displays
- **Action Cameras:** Sports Vlogging, Live Streaming
- **Enterprise Collaboration:** Video Collaboration, Multi-User AI Experiences
- **Drones & Robotics:** Home Robots, Enterprise Drones

## Features

- **7- or 8-core Qualcomm Oryon CPU:** High-speed multitasking and responsive application performance
- **Hexagon V79 Tensor Processor:** Low-power AI inference across vision, audio, and sensor workloads
- **Adreno 8-Series GPU:** High-performance 3D graphics and ray tracing for immersive display systems
- **LPDDR5X memory @ 4800 MHz:** Fast data access and efficient memory bandwidth
- **8K60 decode and 8K30 encode:** Ultra-high-resolution video playback and capture
- **4K240 video decode and 4K120 encode:** High-frame-rate slow-motion and action video workflows
- **Triple 48 MP ZSL ISP:** Simultaneous capture of multiple high-resolution image streams
- **Dual MIPI-DSI and DP v1.4:** Dual 4K or single 8K displays for TVs and advanced monitoring systems
- **UFS 4.0 storage:** Fast boot and quick data streaming for video applications
- **USB 3.1 Gen 2 Type-C with DP:** Unified connectivity for display, power, and data
- **Audio DSP with Qualcomm Aqstic™ codec:** Studio-quality audio for voice control and video sync
- **Always Sensing Camera (ASC):** Continuous monitoring and low-power, wake-on-motion use cases
- **215 GPIOs and 15 I/O buses:** Flexible sensor, motor, and peripheral integration
- **Industrial-grade temperature support:** Reliability in automotive and outdoor installations

## Ordering Information

### Part Numbers

CQ8750S-1-AB  
CQ8725S-2-AA

## Specifications

Dragonwing Q-8750	
SKUs	CQ8750S, CQ8725S
CPU*	Max clock speed of 4.32 GHz powered by the custom 7- or 8-core Qualcomm Oryon CPU
AI Performance*	Up to 77 Dense TOPS; Dependent on SKU configuration
GPU*	Max speed of 1.1 GHz powered by the Adreno 8-series GPU
Memory	4x 16-bit LPDDR5X @ 4800 MHz
Addressable Memory	24 GB
Audio DSP (LPASS)	Hexagon V79 @ 4-thread DSP 5x SoundWire, 8x DMICs, 7x I2S 32-Channel TDM/PCM support @ 48 kHz Qualcomm Aqstic Audio Technologies
Display Support*	Adreno GPU Internal panel resolution up to 3840 x 2560 @ 144 Hz 2x MIPI-DSI, DP v1.4 up to 8K60 8x DSC v1.2 on MIPI-DSI ports
Video Decode	4K @ 240 fps / 8K @ 60 fps Formats: H.264, H.265, VP9, and AV1
Video Encode	4K @ 120 fps / 8K @ 30 fps Formats: H.264 and H.265
Camera*	2x Always Sensing Camera (ASC) Qualcomm Spectra™ Image Signal Processor (ISP) 8-series 3x 48 MP at 30 fps ZSL ISP 6x 4-lane D-PHY 1.2/3-trio C-PHY 2.0 interfaces
PCIe	1x PCIe Gen 3 2-lane
USB	1x USB 3.1 Gen 2 @ 10 Gbps, support USB Type-C with DP v1.4 eUSB 2.0
Other I/O	215x GPIO UART, I2C, I3C, SPI, 10x I2C hubs via QUP Fifteen dedicated buses: 4x I3C/I2C, 3x SPI, 3x I2C, 2x UART, 2x I3C/I2C (for ASC), 1x I2C (for ASC) via sensors interfaces and supported sensors
Storage	1x UFS 4.0 2-lane gear 5 Rate B SD 3.0 4-bit for SD card
Wi-Fi/Bluetooth®/WAN	Wi-Fi 7 and Bluetooth 6 Supported with companion chips
OS	Android 15+ and Linux Yocto
Package	15.95 x 14.0 x 0.60 mm, MPSP1512 PoP
Temp. Range (Tj)	-30 to +105 °C

Specifications are subject to change.

\* Performance may vary by SKU configuration.

To learn more visit: [qualcomm.com](https://www.qualcomm.com)

